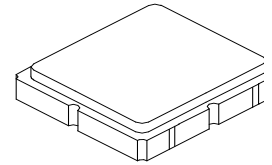




AEC-Q200
This component was always
RoHS compliant from the first
date of manufacture.

SF2198E

**806 MHz
SAW Filter**



SM3030-6

- **Surface Mount 3.0 x 3.0 mm Package**
- **Complies with Directive 2002/95/EC (RoHS)**



Absolute Maximum Ratings

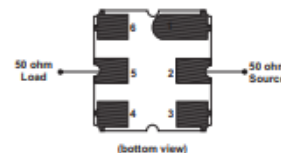
Rating	Value	Units
Input Power Level	10	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature Range	-40 to +85	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Maximum Soldering Profile, 5 cycles/10 seconds maximum	265	°C

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_C			806		MHz
Insertion Loss	IL	791 to 821 MHz		2.9	4.5	dB
		800 to 812 MHz		2.3	3.0	
		805 to 806 MHz		1.8	2.5	
Amplitude Ripple, 791 to 821 MHz				1.3	3.0	
VSWR, 791 to 821 MHz				1.7	2.5	
Attenuation, 0 dB Reference:						dB
DC to 760 MHz			45	55		
760 to 775 MHz			30	48		
832 to 862 MHz			8	15		
862 to 900 MHz			30	39		
900 to 1500 MHz			45	57		
1500 to 2000 MHz			35	45		
Source Impedance	Z_S			50		Ω
Load Impedance	Z_L			50		
Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	928, YWWS					
Standard Reel Quantity	Reel Size 7 Inch					500 Pieces/Reel
	Reel Size 13 Inch					3000 Pieces/Reel

Electrical Connections

Connection	Terminals
Input	2
Output	5
Case Ground	All others

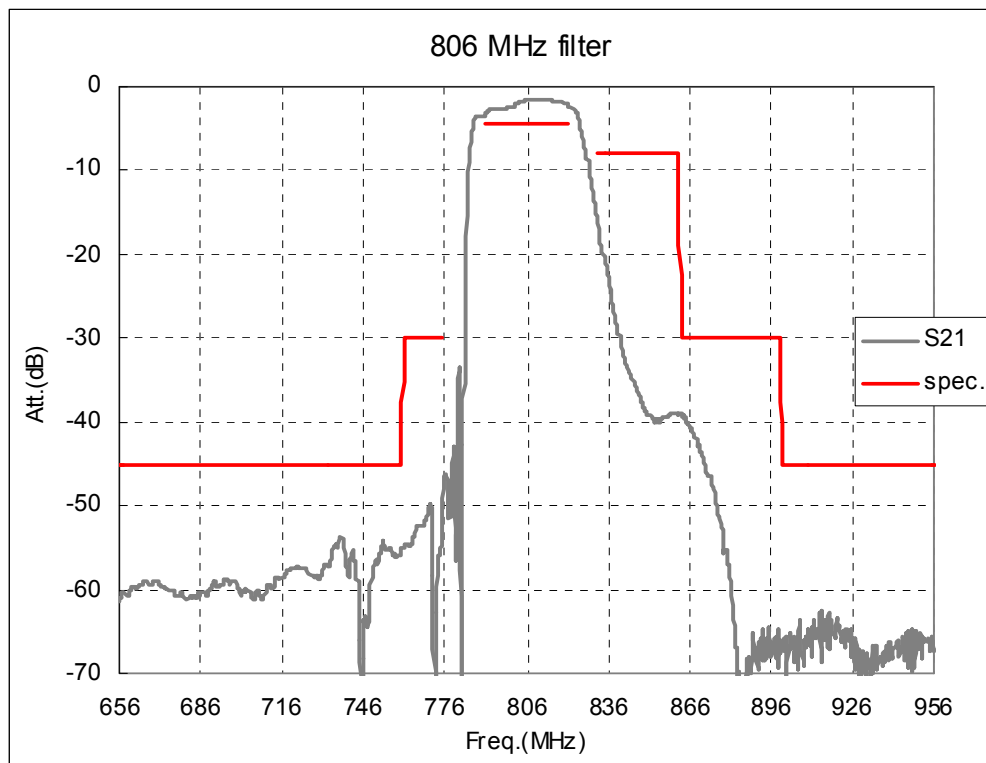
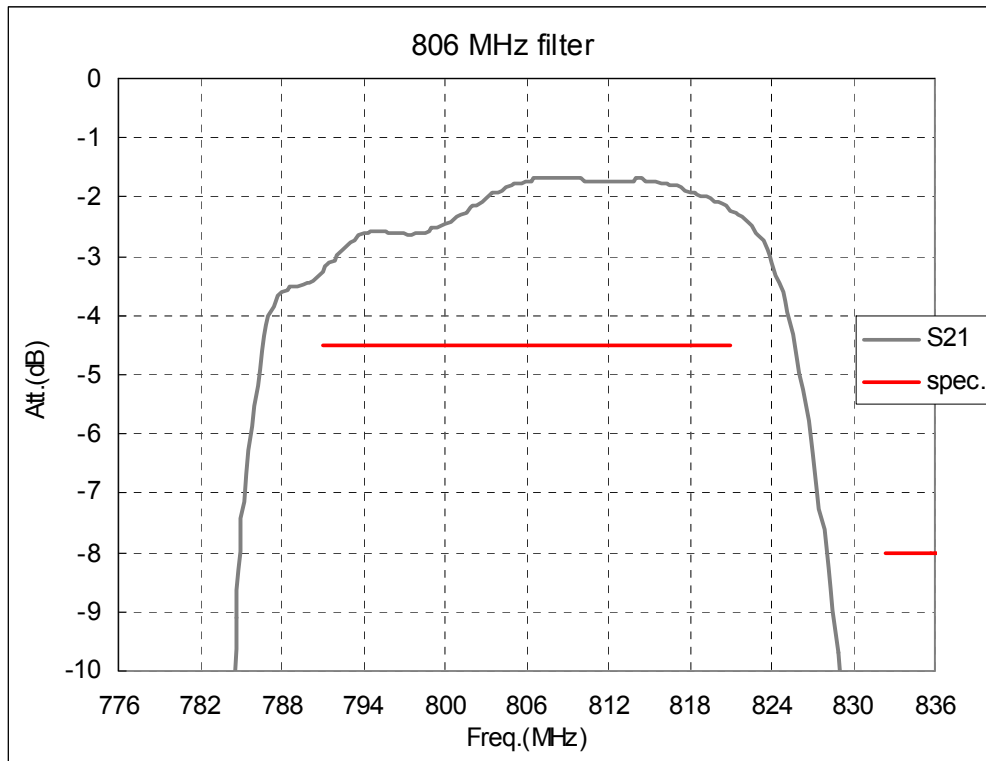


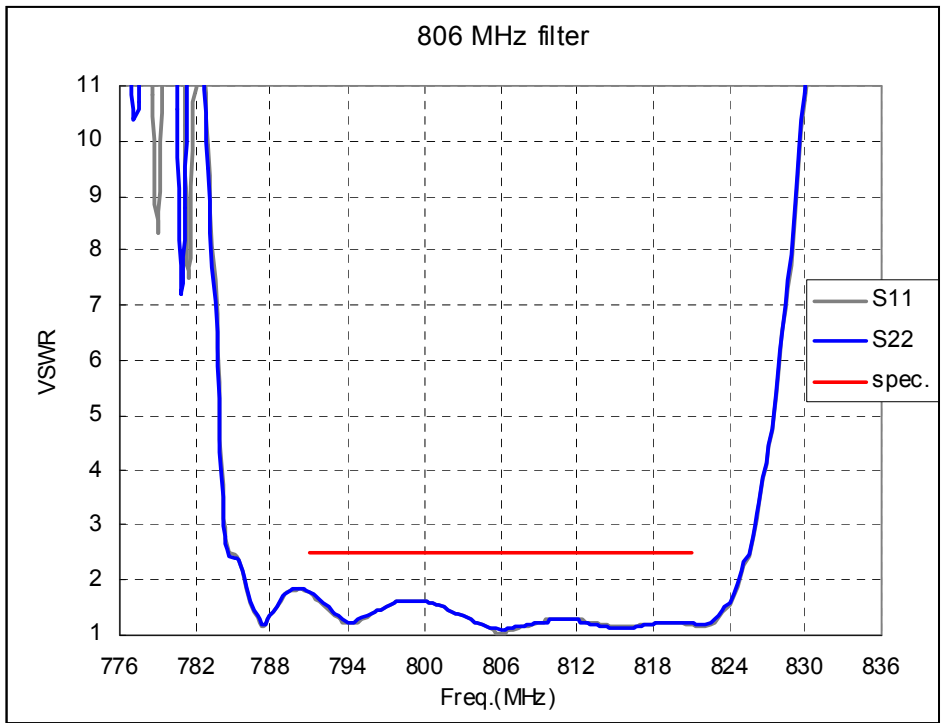
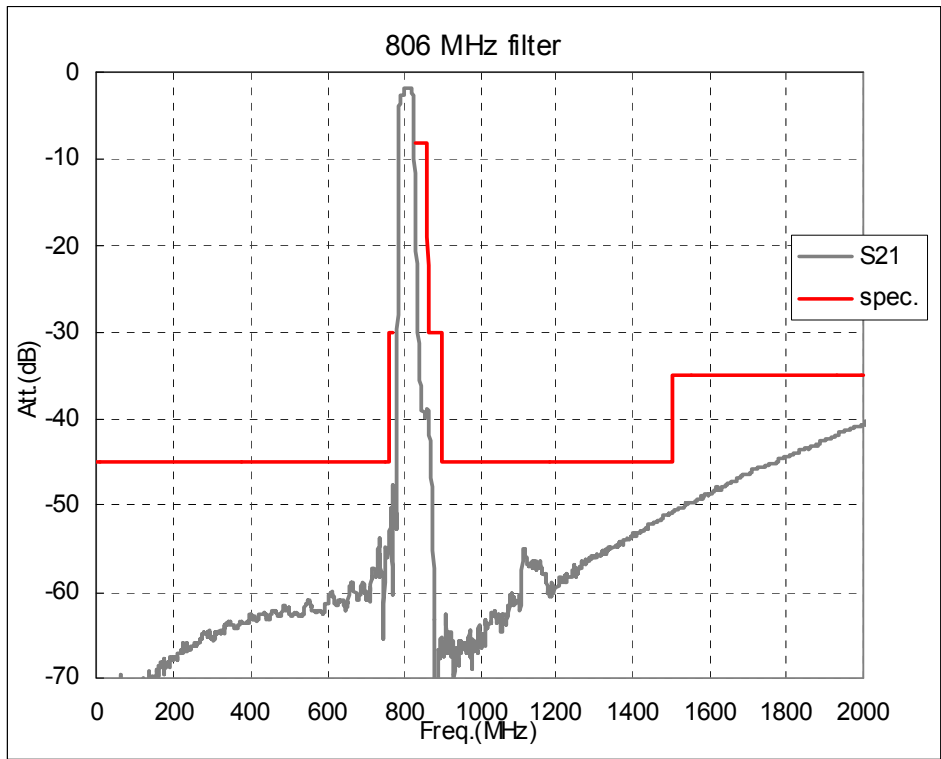
CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.

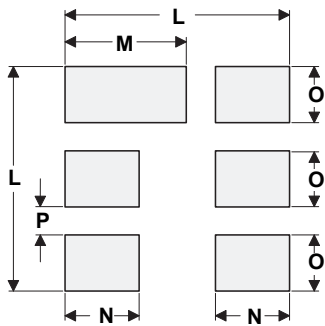
Filter Response Plots





SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

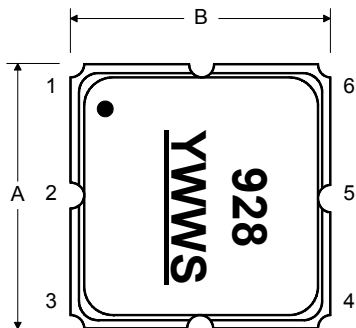
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K	0.62	0.75	0.88	0.024	0.029	0.034
L		3.20			0.126	
M		1.70			0.067	
N		1.05			0.041	
O		0.81			0.032	
P		0.38			0.015	

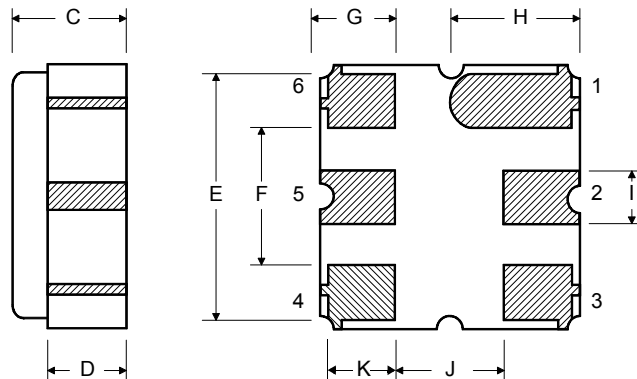
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic
	Pb Free

TOP VIEW



BOTTOM VIEW



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

